



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





SOFT, SILICONE GEL

Tputty™ 504 is a soft silicone gel thermal gap filler ideal for applications where large gap tolerances are present.

The silicone gel is filled with a complex matrix of ceramic fillers to yield superior thermal performance.

Tputty™ 504 is soft and compliant transferring little to no pressure between interfaces. Because Tputty™ 504 has a higher viscosity than grease, it eliminates the bleed and pump-out usually associated with grease. Bond line variances can also be more easily controlled than with traditional thermal pads.

Tputty™ 504 can be applied like grease and is easily dispensable from a wide range of commercially available equipment including screen print, syringe and automated equipment.

FEATURES AND BENEFITS

- Soft and compliant transferring little to no pressure between interfaces
- 1.8 W/mK thermal conductivity
- Available in 10cc, 30cc and 55cc syringes
- Available in 100cc, 170cc and 305cc auto dispense cartridges
- Available in bulk containers from sample jars through 20 kg pails
- Applies like grease and is easily dispensable from a wide range of commercially available equipment including screen print, syringe and automated equipment

APPLICATIONS

- Flip chip microprocessors
- PPGAs, micro BGAs, BGAs
- DSP chips, graphic accelerator chips
- Other high-wattage electronic components
- LED lighting

global solutions: local support.™

Americas: +1.800.843.4556

Europe: +49.8031.2460.0

Asia: +86.755.2714.1166

CLV-customerservice@lairdtech.com

www.lairdtech.com/thermal

	Tputty™ 504	TEST METHOD
Construction & Composition	Ceramic-filled dispensable silicone gel	
Color	Light Grey	Visual
Viscosity @ 23°C, mPa.s (cP) Brookfield RV, TC spindle, Helipath @ 0.5 rpm	4,000,000 to 8,000,000	
Temperature Range	-45°C to 200°C	
Thermal Conductivity	1.8 W/mK	ASTM D5470
Density	2.7 g/cc	
Thermal Impedance Final Thickness @ 0.010"	0.15°C-in ² /W (0.97°C-cm ² /W)	ASTM D5470 (modified)
Thermal Impedance Final Thickness @ 0.020"	0.27°C-in ² /W (1.74°C-cm ² /W)	ASTM D5470 (modified)
Dielectric Strength	500 VAC/mil	ASTM D149
Volume Resistivity	>10 ¹⁴ ohm-cm	ASTM D2240
MSDS	Available upon request	
Outgassing TML, wt% / vol%	0.34 / 0.92	ASTM E595
Outgassing CVCM, wt% / vol%	0.09 / 0.24	ASTM E595

Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.